

Certificate of Registration

Nanoplas, Inc. has achieved Registration status for Heat Cure HCF to the NSF International Registration Guidelines for Proprietary Substances and Nonfood Compounds (2022) .



Nanoplas, Inc.
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March 21, 2024

Registration may be verified at
nsfwhitebook.org



A handwritten signature in blue ink, appearing to read "S. Cole".

Samuel Cole
NSF Nonfood Compounds
Registration Program
Company No: C0077574

Heat Cure HCF

Category Code: M1

NSF Registration No. 169605

This product is acceptable for use as a mold release agent (M1) on molds that are used to produce packaging material that will contact food to prevent the finished product from adhering to the mold. The amount used on the equipment should be the minimum required to accomplish the effect.

Registration of this product is current when the NSF Registration Mark and Category Code appear on the product label reviewed by NSF, and the Registered product name is in the NSF White Book™ (www.nsfwhitebook.org).

Listing of all registered nonfood compounds by NSF International is not an endorsement of those compounds or of any performance or efficacy claims made by the manufacturer.